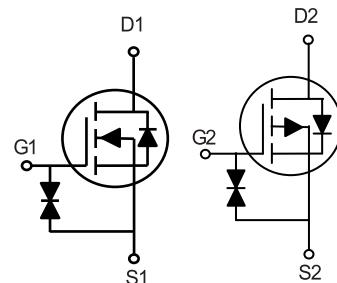


## N and P-Channel Enhancement Mode Power MOSFET

### Description

The RM2020ES9 uses advanced trench technology to provide excellent  $R_{DS(ON)}$  and low gate charge . The complementary MOSFETs may be used to form a level shifted high side switch, and for a host of other applications.

### Equivalent Circuit



### General Features

- N-Channel

$V_{DS} = 20V, I_D = 0.75A$

$R_{DS(ON)} < 380 m\Omega @ V_{GS}=4.5V$

$R_{DS(ON)} < 450 m\Omega @ V_{GS}=2.5V$

$R_{DS(ON)} < 800 m\Omega @ V_{GS}=1.8V$

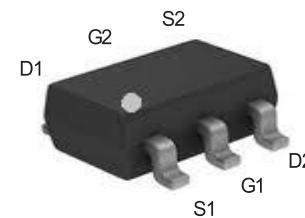
- P-Channel

$V_{DS} = -20V, I_D = -0.8A$

$R_{DS(ON)} < 800 m\Omega @ V_{GS}=-4.5V$

$R_{DS(ON)} < 1200m\Omega @ V_{GS}=-2.5V$

- High power and current handing capability
- Lead free product is acquired
- Surface mount package
- Halogen-free



**SOT-363**

### Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
2020	RM2020ES9	SOT-363-6L	Ø180mm	8mm	3000units

### Absolute Maximum Ratings ( $T_A=25^\circ C$ unless otherwise noted)

Parameter	Symbol	N-Channel	P-Channel	Unit
Drain-Source Voltage	$V_{DS}$	20	-20 (typ.-25)	V
Gate-Source Voltage	$V_{GS}$	$\pm 12$	$\pm 12$	V
Continuous Drain Current $ T_A=25^\circ C $	$I_D$	0.75	-0.8	A
Pulsed Drain Current <sup>(Note 1)</sup>	$I_{DM}$	5	-4	A
Maximum Power Dissipation $ T_A=25^\circ C $	$P_D$	0.15	0.8	W
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 150	-55 To 150	°C

### Thermal Characteristic

Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	N-Ch	833	°C/W
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	P-Ch	156	°C/W

## Electrical Characteristics ( $T_A = 25^\circ\text{C}$ Unless Otherwise Noted )

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static Characteristics</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{ V}$ , $I_{DS} = -250\text{ }\mu\text{A}$	-20	-	-	V
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$ , $I_{DS} = -250\text{ }\mu\text{A}$	-0.3	-0.65	-1.0	V
$I_{DSS}$	Drain Leakage Current	$V_{DS} = -20\text{ V}$ , $V_{GS} = 0\text{ V}$ $T_J = 85^\circ\text{C}$	-	-	-1 -30	$\mu\text{A}$
$I_{GSS}$	Gate Leakage Current	$V_{GS} = \pm 8\text{ V}$ , $V_{DS} = 0\text{ V}$	-	-	$\pm 10$	$\mu\text{A}$
$R_{DS(\text{ON})}^{\text{a}}$	On-State Resistance	$V_{GS} = -4.5\text{ V}$ , $I_{DS} = -0.5\text{ A}$	-	0.85	1.2	$\Omega$
		$V_{GS} = -2.5\text{ V}$ , $I_{DS} = -0.2\text{ A}$	-	1.05	1.5	
		$V_{GS} = -1.5\text{ V}$ , $I_{DS} = -0.04\text{ A}$	-	1.5	-	
		$V_{GS} = -1.2\text{ V}$ , $I_{DS} = -0.01\text{ A}$	-	2	-	
<b>Diode Characteristics</b>						
$V_{SD}^{\text{a}}$	Diode Forward Voltage	$I_{SD} = -0.5\text{ A}$ , $V_{GS} = 0\text{ V}$	-	-	1.3	V
$t_{rr}$	Reverse Recovery Time	$I_{SD} = -0.5\text{ A}$ , $dI_{SD}/dt = 100\text{ A}/\mu\text{s}$	-	70	-	ns
$Q_{rr}$	Reverse Recovery Charge		-	68	-	nC
<b>Dynamic Characteristics<sup>b</sup></b>						
$C_{iss}$	Input Capacitance	$V_{GS} = 0\text{ V}$ , $V_{DS} = -10\text{ V}$ Frequency = 1 MHz	-	87	-	pF
$C_{oss}$	Output Capacitance		-	15	-	
$C_{rss}$	Reverse Transfer Capacitance		-	8.2	-	
$t_d(\text{on})$	Turn-on Delay Time	$V_{DS} = -30\text{ V}$ , $V_{GEN} = -10\text{ V}$ , $R_G = 25\text{ }\Omega$ , $R_L = 60\text{ }\Omega$ , $I_{DS} = -0.67\text{ A}$	-	5.6	-	ns
$t_r$	Turn-on Rise Time		-	5.3	-	
$t_d(\text{off})$	Turn-off Delay Time		-	30	-	
$t_f$	Turn-off Fall Time		-	21	-	
$Q_g$	Total Gate Charge	$V_{GS} = -4.5\text{ V}$ , $V_{DS} = -10\text{ V}$ , $I_{DS} = -0.67\text{ A}$	-	1.8	-	nC
$Q_{gs}$	Gate-Source Charge		-	0.82	-	
$Q_{gd}$	Gate-Drain Charge		-	0.59	-	

Notes :

a : Pulse test ; pulse width  $\leq 300\text{ }\mu\text{s}$ , duty cycle  $\leq 2\%$

b : Guaranteed by design, not subject to production testing

## MOSFET ELECTRICAL CHARACTERISTICS $T_a=25^\circ\text{C}$ unless otherwise specified

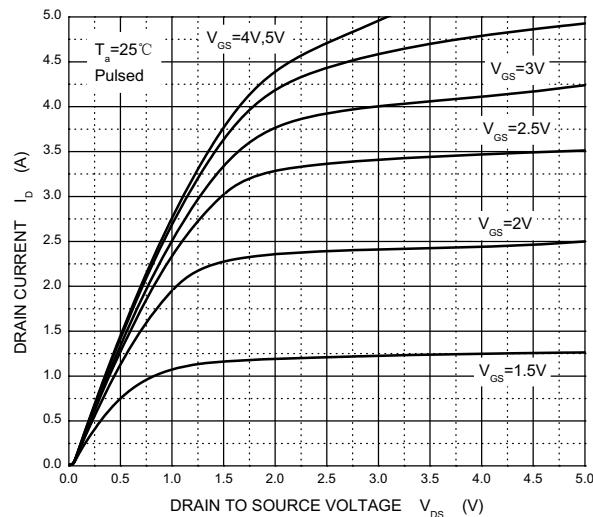
Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
<b>STATIC PARAMETERS</b>						
Drain-source breakdown voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	20			V
Zero gate voltage drain current	$I_{\text{DSS}}$	$V_{\text{DS}} = 20\text{V}, V_{\text{GS}} = 0\text{V}$			1	$\mu\text{A}$
Gate-body leakage current	$I_{\text{GSS}}$	$V_{\text{GS}} = \pm 10\text{V}, V_{\text{DS}} = 0\text{V}$			$\pm 20$	$\mu\text{A}$
Gate threshold voltage (note 1)	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	0.35	0.54	1.1	V
Drain-source on-resistance (note 1)	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 4.5\text{V}, I_D = 0.65\text{A}$		270	380	$\text{m}\Omega$
		$V_{\text{GS}} = 2.5\text{V}, I_D = 0.55\text{A}$		320	450	$\text{m}\Omega$
		$V_{\text{GS}} = 1.8\text{V}, I_D = 0.45\text{A}$		390	800	$\text{m}\Omega$
Forward transconductance (note 1)	$g_{\text{FS}}$	$V_{\text{DS}} = 10\text{V}, I_D = 0.8\text{A}$		1.6		S
Diode forward voltage(note 1)	$V_{\text{SD}}$	$I_S = 0.15\text{A}, V_{\text{GS}} = 0\text{V}$			1.2	V
<b>DYNAMIC PARAMETERS (note 2)</b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}} = 16\text{V}, V_{\text{GS}} = 0\text{V}, f = 1\text{MHz}$		79	120	pF
Output Capacitance	$C_{\text{oss}}$			13	20	pF
Reverse Transfer Capacitance	$C_{\text{rss}}$			9	15	pF
<b>SWITCHING PARAMETERS(note 2)</b>						
Turn-on delay time	$t_{\text{d}(\text{on})}$	$V_{\text{GS}} = 4.5\text{V}, V_{\text{DS}} = 10\text{V}, I_D = 0.5\text{A}, R_{\text{GEN}} = 10\Omega$		6.7		ns
Turn-on rise time	$t_r$			4.8		ns
Turn-off delay time	$t_{\text{d}(\text{off})}$			17.3		ns
Turn-off fall time	$t_f$			7.4		ns
Total Gate Charge	$Q_g$	$V_{\text{DS}} = 10\text{V}, V_{\text{GS}} = 4.5\text{V}, I_D = 0.25\text{A}$		1.2		nC
Gate-Source Charge	$Q_{\text{gs}}$			0.28		nC
Gate-Drain Charge	$Q_{\text{gd}}$			0.2		nC

**Notes :**

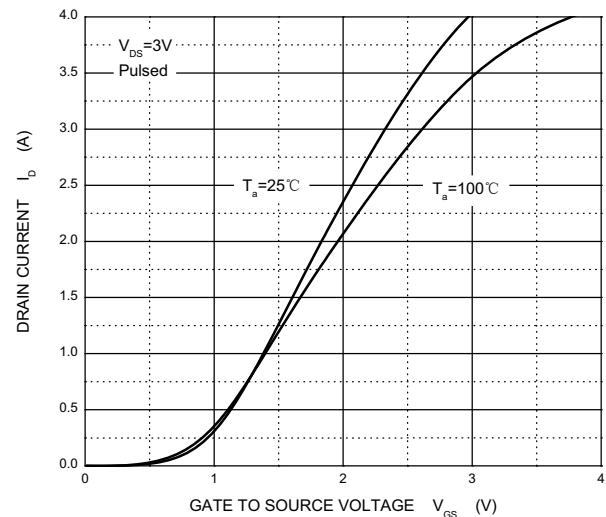
1. Pulse Test : Pulse width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 0.5\%$ .
2. Guaranteed by design, not subject to production testing.

# N-TypicalCharacteristics

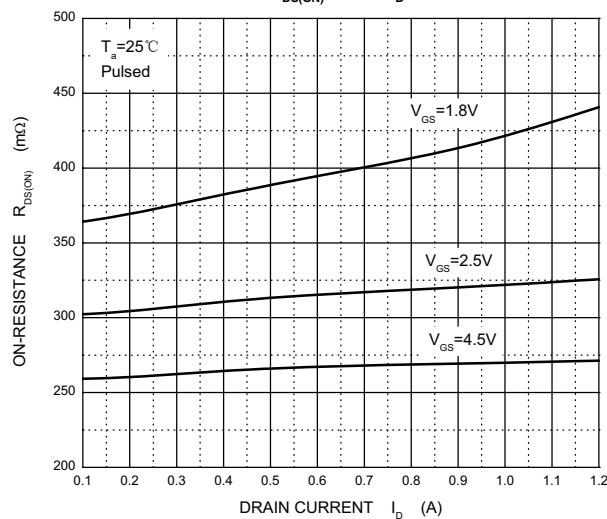
**Output Characteristics**



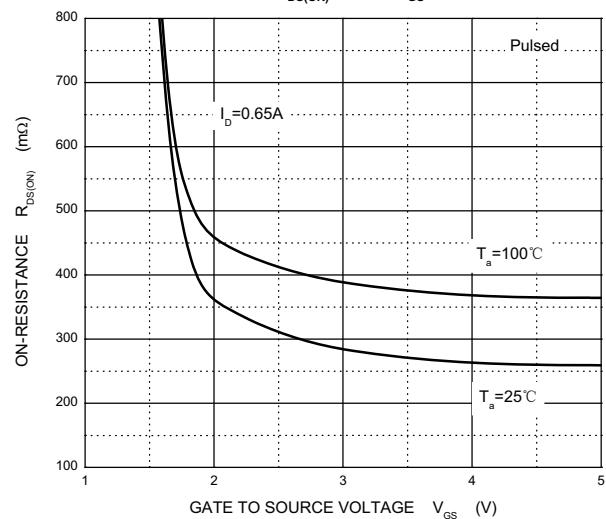
**Transfer Characteristics**



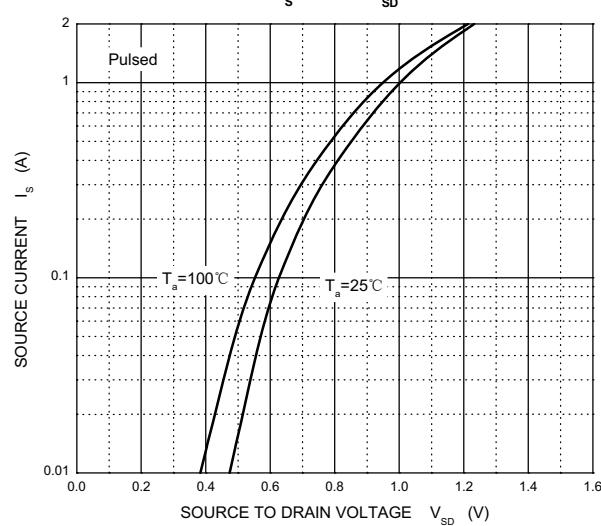
$R_{DS(ON)}$  —  $I_D$



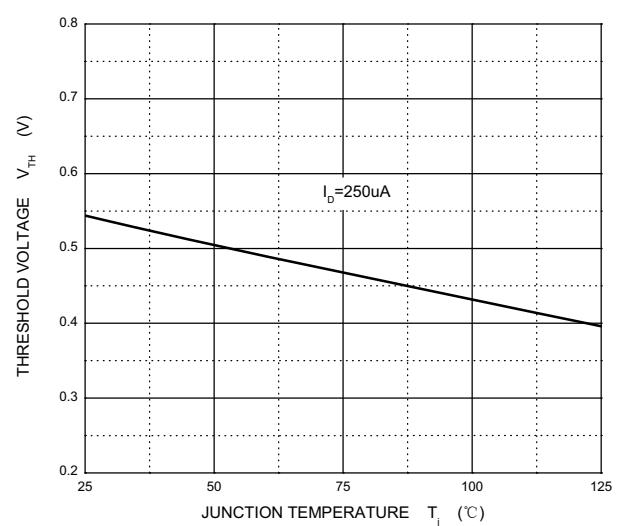
$R_{DS(ON)}$  —  $V_{GS}$



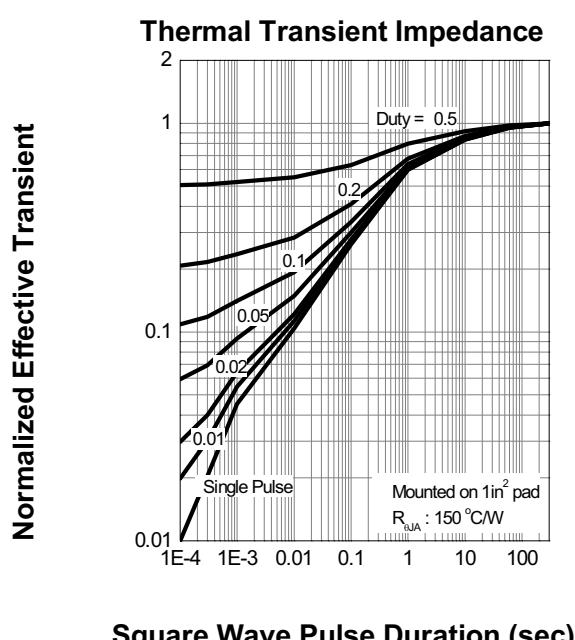
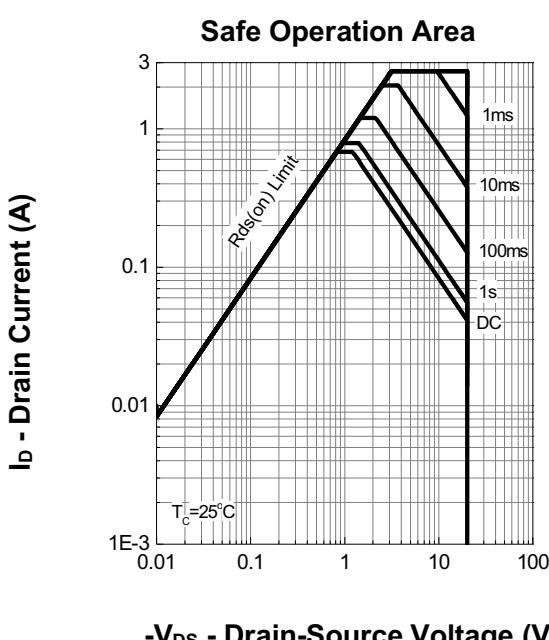
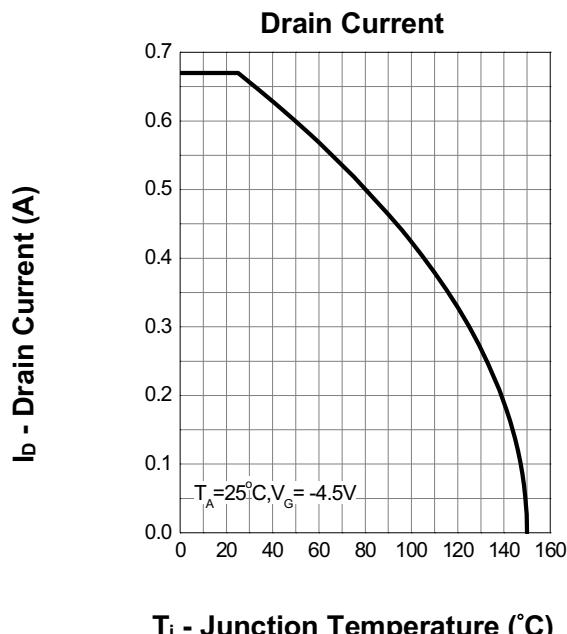
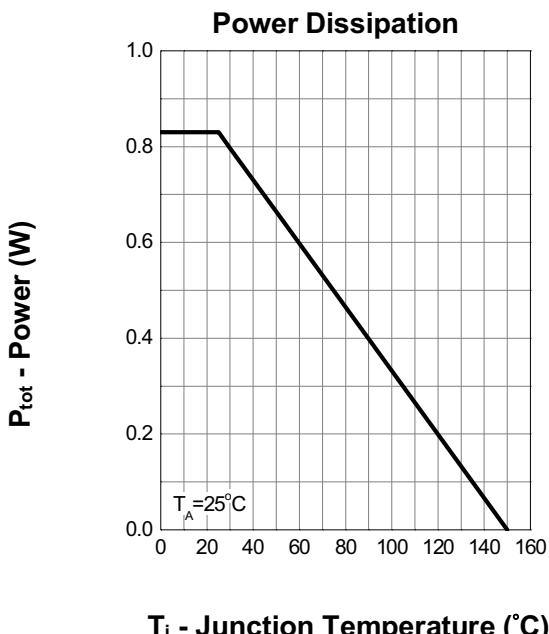
$I_s$  —  $V_{SD}$



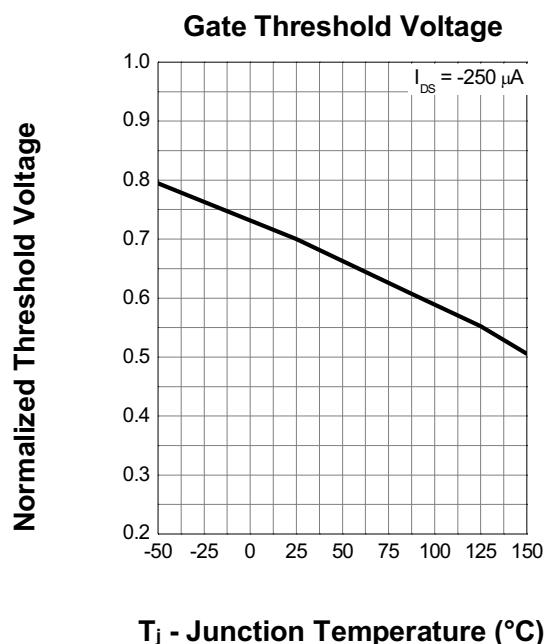
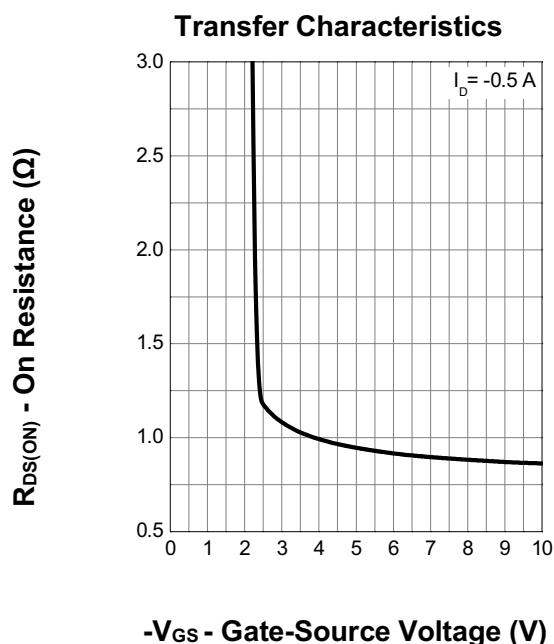
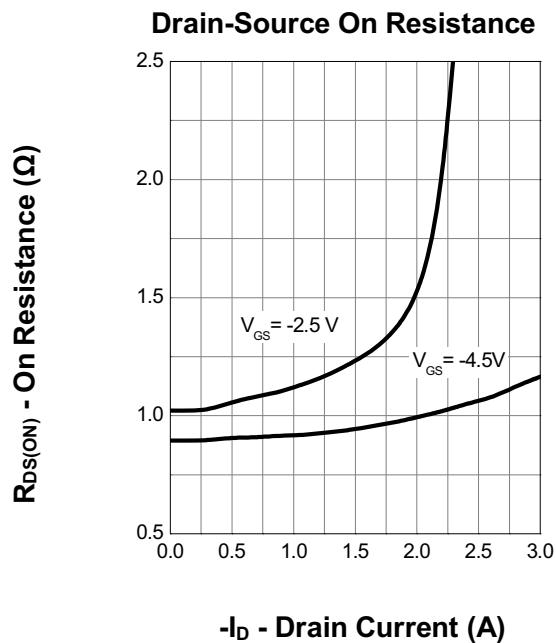
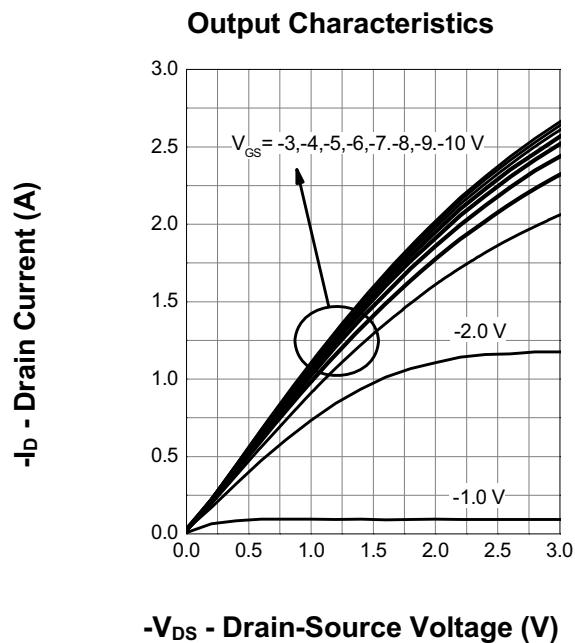
**Threshold Voltage**



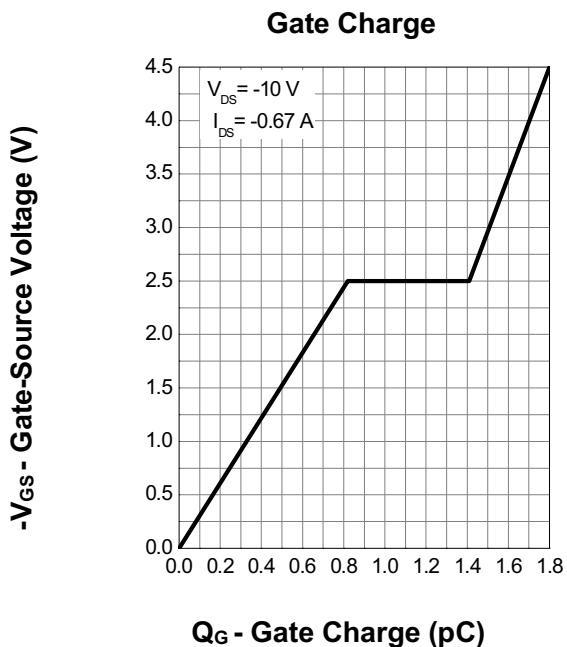
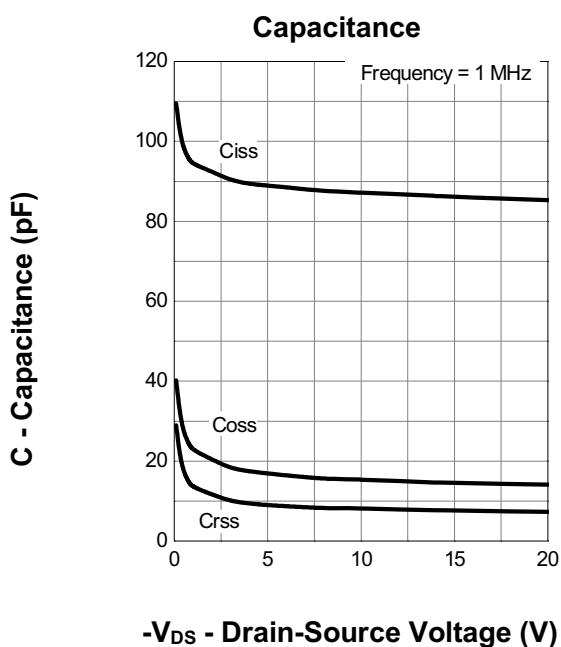
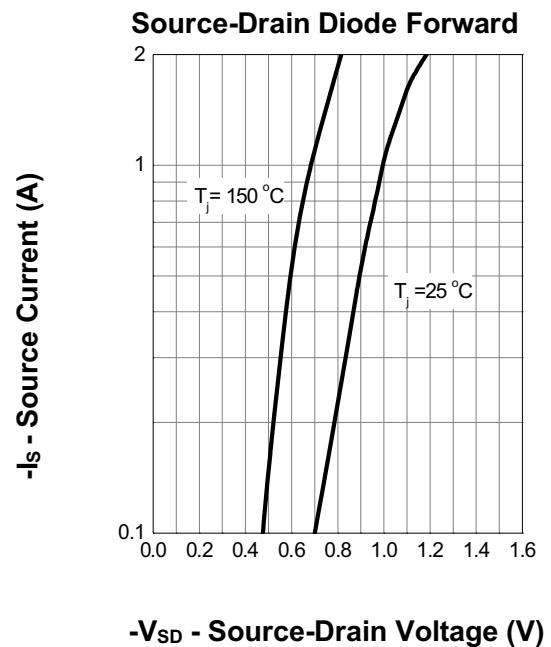
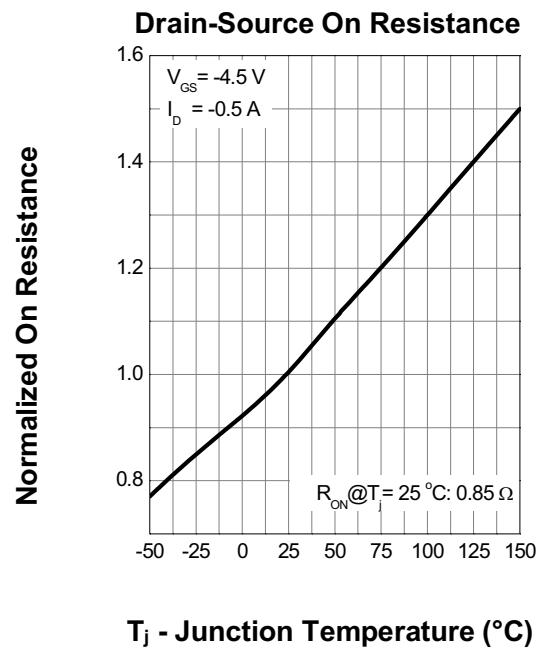
## P-Typical Characteristics



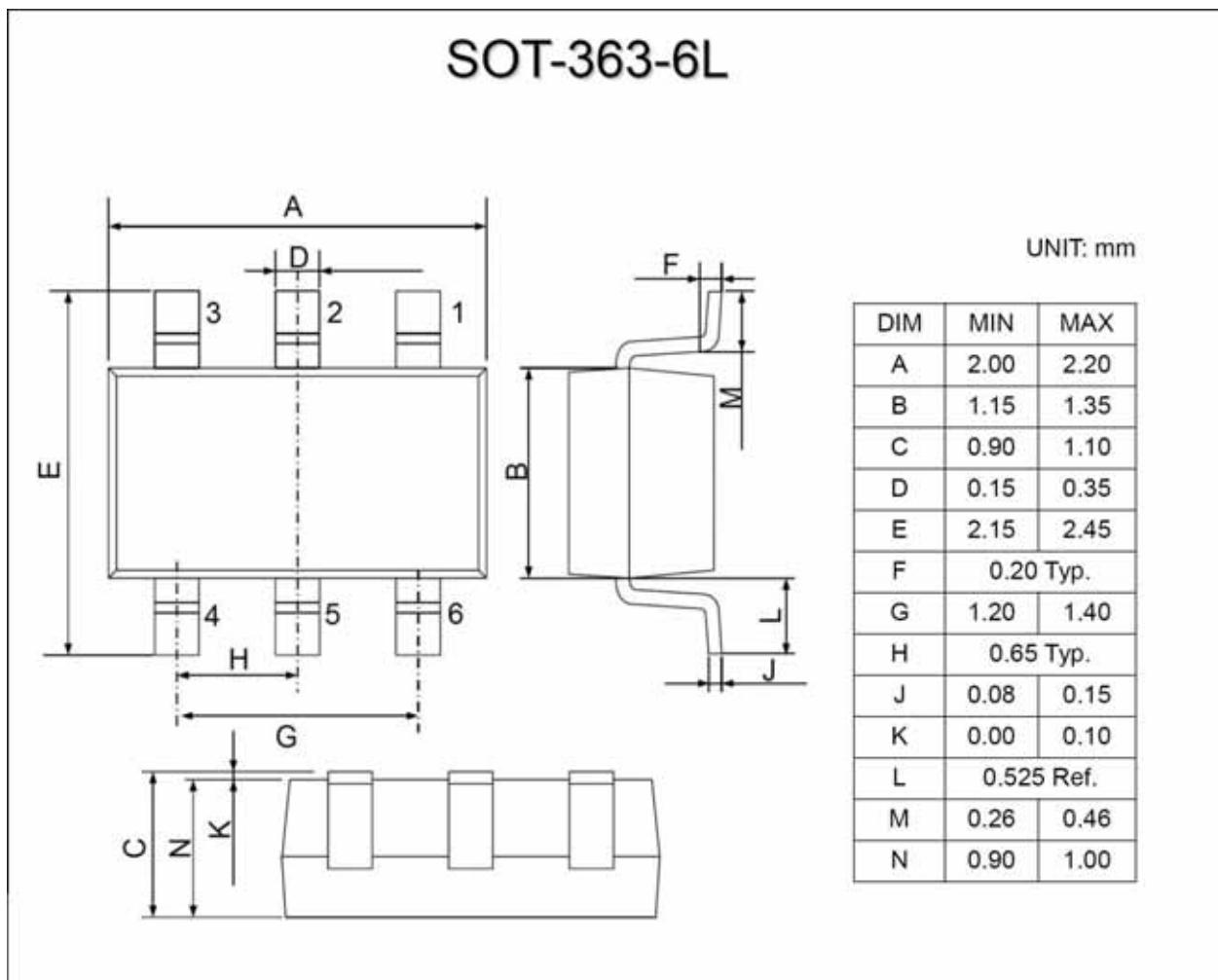
## P-Typical Characteristics



## P-Typical Characteristics



## Package Dimensions



PKG	tape	Reel	Box	pcs/reel	reel/box	pcs/box	box/carton	pcs/carton
SOT-363	IC-ZD-05	7" (IC-JP-05)	SOT363	3000	10	30000	4	120000

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